



## Material Content Data Sheet



Sales Product Name	BSB012NE2LX			Issued		29. August 2013		
MA#	MA000856722							
Package	MG-WDSO-N-2-8			Weight*		83.42 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.882	4.65	4.65	46539	46539
leadframe	non noble metal	copper	7440-50-8	74.415	89.22	89.22	892037	892037
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.25		2532	
	noble metal	silver	7440-22-4	0.840	1.01	1.26	10069	12601
plating	non noble metal	nickel	7440-02-0	0.211	0.25	0.25	2532	2532
glue	plastics	epoxy resin	-	0.178	0.21		2137	
	noble metal	silver	7440-22-4	1.095	1.31	1.52	13127	15264
solder	non noble metal	copper	7440-50-8	0.011	0.01		132	
	noble metal	silver	7440-22-4	0.066	0.08		790	
	non noble metal	tin	7440-31-5	2.119	2.54	2.63	25396	26318
passivation	plastics	epoxy resin	-	0.393	0.47	0.47	4709	4709
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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